The T-4909 is a manual, high quality die bonder with superior ergonomic design. As with all of Tresky’s products, the T-4909 incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

**T-4909 Application Packages:**
- Epoxy
- Eutectic
- Ultrasonic
Excellent performance, ergonomically designed and high reliability makes the T-4909 ideal for small and medium volume production.

APPLICATIONS:

Die Attach, MEMS, MOEMS, VCSEL, RFID, Adhesive Bonding, Eutectic Bonding (AuAu, ....), ....

FEATURES AND OPTIONS:

- **TRUE VERTICAL TECHNOLOGY™**
  Z-movement 60mm with 360° Tool rotation; Dispenser, Stamping, Scrub, Tool Heating, Pre Form Spindle, ...

- **XY air-cushioned placement stage**
  with micrometer control, supporting: Waffle - / Gel - Pack -, Substrate - Holder, various Heating Plates.

TECHNICAL DATA:

<table>
<thead>
<tr>
<th>Specification</th>
<th>Details</th>
</tr>
</thead>
<tbody>
<tr>
<td>XY- Movement (placement stage):</td>
<td>180mm x 180mm (manual)</td>
</tr>
<tr>
<td>Z- Movement:</td>
<td>60mm (manual)</td>
</tr>
<tr>
<td>Spindle Rotation:</td>
<td>360°</td>
</tr>
<tr>
<td>Placement accuracy:</td>
<td>10µm (process depending)</td>
</tr>
<tr>
<td>Connections:</td>
<td>Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)</td>
</tr>
<tr>
<td>Dimensions:</td>
<td>755mm x 730mm x 500mm</td>
</tr>
<tr>
<td>Weight:</td>
<td>30kg</td>
</tr>
<tr>
<td>Voltage:</td>
<td>110V / 220V</td>
</tr>
</tbody>
</table>

Note: All specifications are subject to change without notice

REPRESENTED BY:

HEADQUATERS

**Dr. TRESKY AG**  
Boehnirainstr: 13  
CH-8800 Thalwil  
Switzerland  
Tel.: +41 44 772 1941  
Fax: +41 44 772 1945  
tresky@tresky.com

**TRESKY GmbH**  
Oranienburger Chaussee 31-33  
D-16548 Glienike / Nordbahn (Berlin)  
Germany  
Tel.: +49 33056 275 411  
Fax: +49 33056 430 235  
info@tresky.com

**TRESKY Corporation**  
704 Ginesi Drive, Suite 11A  
Morganville, NJ 07751  
USA  
Tel.: +1 732 536 8600  
Fax: +1 732 536 0495  
sales@tresky.com

www.tresky.com